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# 2.5V / 3.3V Differential 4:1 Mux w/Input Equalizer to 1:2 LVPECL Clock/Data Fanout / Translator

# Multi-Level Inputs w/ Internal Termination

The NB6LQ572 is a high performance differential 4:1 Clock/Data input multiplexer and a 1:2 LVPECL Clock / Data fanout buffer that operates up to 5 GHz / 6.5 Gbps respectively with a 2.5 V or 3.3 V power supply.

Each INx/INx input pair incorporates a fixed Equalizer Receiver, which when placed in series with a Clock / Data path, will enhance the degraded signal transmitted across an FR4 backplane or cable interconnect. For applications that do not require Equalization, consider the NB6L572, which is pin-compatible to the NB6LQ572.

The differential Clock / Data inputs have internal 50  $\Omega$  termination resistors and will accept differential LVPECL, CML, or LVDS logic levels. The NB6LQ572 incorporates a pair of Select pins that will choose one of four differential inputs and will produce two identical LVPECL output copies of Clock or Data. As such, the NB6LQ572 is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The two differential LVPECL outputs will swing 750 mV when externally loaded and terminated with a 50  $\Omega$  resistor to  $V_{CC}-2$  V and are optimized for low skew and minimal jitter.

The NB6LQ572 is offered in a low profile 5x5 mm 32-pin QFN Pb-Free package. Application notes, models, and support documentation are available at www.onsemi.com.

The NB6LQ572 is a member of the ECLinPS MAX<sup>™</sup> family of high performance clock products.

#### Features

- Input Data Rate > 6.5 Gb/s Typical
- Data Dependent Jitter < 10 ps
- Maximum Input Clock Frequency > 5 GHz Typical
- Random Clock Jitter < 0.8ps RMS
- Fixed Input Equalization
- Low Skew 1:2 LVPECL Outputs, < 15 ps max
- 4:1 Multi-Level Mux Inputs, accepts LVPECL, CML LVDS
- 150ps Typical Propagation Delay
- 55ps Typical Rise and Fall Times
- Differential LVPECL Outputs, 800 mV peak-to-peak, typical
- Operating Range:  $V_{CC} = 2.375 \text{ V}$  to 3.6 V
- Internal 50 Ω Input Termination Resistors
- V<sub>REFAC</sub> Reference Output
- QFN-32 Package, 5mm x 5mm
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



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#### QFN32 MN SUFFIX CASE 488AM

DIAGRAM O NB6L O572

**MARKING** 

NB6L Q572 AWLYYWW•

A = Assembly Location

WL = Wafer Lot
YY = Year
WW = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 9 of this data sheet.

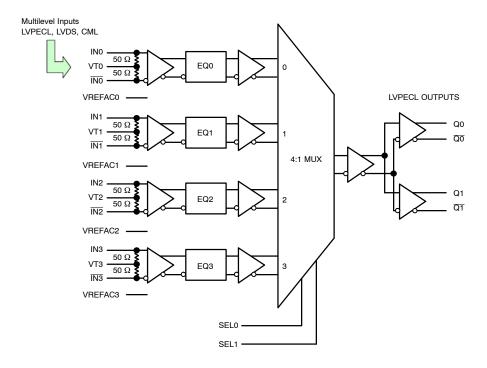


Figure 1. Simplified Block Diagram

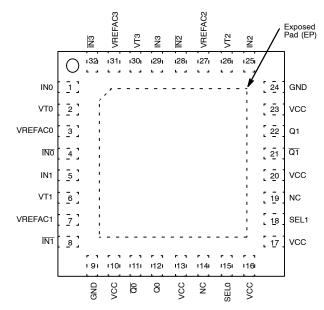


Figure 2. Pinout: QFN-32 (Top View)

**Table 1. Input Select Function Table** 

SEL1*	SEL0*	Clock / Data Input Selected	
0	0	IN0 Input Selected	
0	1	IN1 Input Selected	
1	0	IN2 Input Selected	
1	1	IN3 Input Selected	

<sup>\*</sup>Defaults HIGH when left open.

**Table 2. PIN DESCRIPTION** 

Pin Num- ber	Pin Name	I/O	Pin Description
1, 4 5, 8 25, 28 29, 32	INO, <u>INO</u> IN1, <u>IN1</u> IN2, <u>IN2</u> IN3, <u>IN3</u>	LVPECL, CML, LVDS Input	Noninverted, Inverted, Differential Clock or Data Inputs
2, 6 26, 30	VT0, VT1 VT2, VT3		Internal 100 $\Omega$ Center–tapped Termination Pin for INx / $\overline{\text{INx}}$
15 18	SEL0 SEL1	LVTTL/LVCMOS Input	Input Select pins, default HIGH when left open through a 94 k $\Omega$ pullup resistor. Input logic threshold is V <sub>CC</sub> / 2. See Select Function, Table 1.
14, 19	NC	-	No Connect
10, 13, 16 17, 20, 23	V <sub>CC</sub>	-	Positive Supply Voltage.
11, 12 21, 22	Q0, Q0 Q1, Q1	LVPECL Output	Non-inverted, Inverted Differential Outputs.
9, 24	GND		Negative Supply Voltage
3 7 27 31	VREFAC0 VREFAC1 VREFAC2 VREFAC3	-	Output Voltage Reference for Capacitor-Coupled Inputs
-	EP	-	The Exposed Pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically connected to GND.

In the differential configuration when the input termination pins (VT0, VT1, VT2, VT3) are connected to a common termination voltage or left open, and if no signal is applied on INx/INx input, then the device will be susceptible to self–oscillation.
 All V<sub>CC</sub> and GND pins must be externally connected to a power supply for proper operation.

**Table 3. ATTRIBUTES** 

Characterist	Value			
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V		
R <sub>PU</sub> - SELx Input Pull-up Resistor		94 kΩ		
Moisture Sensitivity (Note 3)	QFN-32	Level 1		
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
Transistor Count	221			
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test				

<sup>3.</sup> For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS** 

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		-0.5 to +4.0	V
V <sub>IN</sub>	Positive Input Voltage	GND = 0 V		-0.5 to V <sub>CC</sub> +0.5	V
V <sub>INPP</sub>	Differential Input Voltage $ IN - \overline{IN} $			1.89	V
l <sub>OUT</sub>	LVPECL Output Current	Continuous Surge		50 100	mA
I <sub>IN</sub>	Input current Through RT (50 Ω resistor)			± 40	mA
I <sub>VREFAC</sub>	V <sub>REFAC</sub> Sink or Source Current			±1.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	QFN-32 QFN-32	31 27	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case) (Note 4)		QFN-32	12	°C/W
T <sub>sol</sub>	Wave Solder	≤ 20 sec		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

<sup>4.</sup> JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS POSITIVE LVPECL OUTPUT  $V_{CC}$  = 2.375 V to 3.6 V, GND = 0 V,  $T_A$  = -40°C to +85°C (Note 5)

Symbol	Characteristic	Min	Тур	Max	Unit
POWER S	SUPPLY		•		
V <sub>CC</sub>	Power Supply Voltage $ \begin{array}{c} V_{CC} = 2.5 \ V \\ V_{CC} = 3.3 \ V \end{array} $	2.375 3.0	2.5 3.3	2.625 3.6	٧
I <sub>CC</sub>	Power Supply Current for V <sub>CC</sub> (Inputs and Outputs Open)		75	110	mA
LVPECL (	DUTPUTS			•	•
V <sub>OH</sub>	Output HIGH Voltage (Note 6)	V <sub>CC</sub> – 1145 1355 2155	V <sub>CC</sub> - 900 1600 2400	V <sub>CC</sub> - 800 1700 2500	mV
V <sub>OL</sub>	Output LOW Voltage (Note 6)	V <sub>CC</sub> – 2000 500 1300	V <sub>CC</sub> - 1700 800 1600	V <sub>CC</sub> - 1500 1000 1800	mV
DIFFERE	NTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Note 7) (Figure	es 5 and 6)	•	•	
V <sub>IH</sub>	Single-ended Input HIGH Voltage	V <sub>th</sub> + 100		V <sub>CC</sub>	mV
V <sub>IL</sub>	Single-ended Input LOW Voltage	GND		V <sub>th</sub> – 100	mV
V <sub>th</sub>	Input Threshold Reference Voltage Range (Note 8)	1100		V <sub>CC</sub> – 100	mV
V <sub>ISE</sub>	Single-ended Input Voltage (V <sub>IH</sub> - V <sub>IL</sub> )	200		1200	mV
VREFAC					
V <sub>REFAC</sub>	Output Reference Voltage (100 μA Load)	V <sub>CC</sub> – 1300	V <sub>CC</sub> – 1100	V <sub>CC</sub> – 900	mV
DIFFERE	NTIAL INPUTS DRIVEN DIFFERENTIALLY (Note 9) (Figures 7 and	d 8)			
$V_{IHD}$	Differential Input HIGH Voltage (IN <sub>x</sub> , $\overline{\text{IN}}_{\text{x}}$ )	1200		V <sub>CC</sub>	mV
$V_{\text{ILD}}$	Differential Input LOW Voltage (IN $_{\rm X}$ , $\overline{\rm IN}_{\rm X}$ )	0		V <sub>IHD</sub> – 100	mV
$V_{\text{ID}}$	Differential Input Voltage (IN <sub>x</sub> , $\overline{\text{IN}}_{\text{X}}$ ) (V <sub>IHD</sub> – V <sub>ILD</sub> )	100		1200	mV
V <sub>CMR</sub>	Input Common Mode Range (Differential Configuration) (Note 10) (Figure 9)	1150		V <sub>CC</sub> – 50	mV
I <sub>IH</sub>	Input HIGH Current IN <sub>x</sub> /IN <sub>x</sub> (VT <sub>x</sub> /VT <sub>x</sub> Open)	-150		150	μΑ
I <sub>IL</sub>	Input LOW Current IN <sub>x</sub> /IN <sub>x</sub> (VT <sub>x</sub> /VT <sub>x</sub> Open)	-150		150	μΑ
CONTRO	L INPUT (SELx Pin)				
$V_{IH}$	Input HIGH Voltage for Control Pin	2.0		V <sub>CC</sub>	V
$V_{IL}$	Input LOW Voltage for Control Pin	GND		0.8	V
I <sub>IH</sub>	Input HIGH Current	-150		150	μΑ
I <sub>IL</sub>	Input LOW Current	-150		150	μΑ
TERMINA	TION RESISTORS				
R <sub>TIN</sub>	Internal Input Termination Resistor (Measured from INx to VTx)	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input and Output parameters vary 1:1 with  $V_{CC}$ .
  6. LVPECL outputs loaded with 50  $\Omega$  to  $V_{CC}$  2 V for proper operation.
- Vth, V<sub>IH</sub>, V<sub>IL</sub>, and V<sub>ISE</sub> parameters must be complied with simultaneously.
   Vth is applied to the complementary input when operating in single-ended mode.
- 9. V<sub>IHD</sub>, V<sub>ILD</sub>, V<sub>ID</sub> and V<sub>CMR</sub> parameters must be complied with simultaneously.
  10. V<sub>CMR</sub> min varies 1:1 with GND, V<sub>CMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>CMR</sub> range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS  $V_{CC} = 2.375 \text{ V}$  to 3.6 V, GND = 0 V,  $T_A = -40^{\circ}\text{C}$  to +85°C (Note 11)

Symbol	Characteristic		Min	Тур	Max	Unit
f <sub>MAX</sub>	Maximum Input Clock Frequency	$V_{OUT} \ge 450 \text{ mV}$	5	6		GHz
f <sub>DATAMAX</sub>	Maximum Operating Data Rate	NRZ, (PRBS23)	6.5	8		Gbps
f <sub>SEL</sub>	Maximum Toggle Frequency, SELx		4	10		MHz
V <sub>OUTPP</sub>	Output Voltage Amplitude (@ V <sub>INPPmin</sub> ) f <sub>in</sub> ≤ 5 GHz	(Note 11) (Figures 3 and 10)	450	800		mV
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Differential Outputs Measured at Differential Crosspoint	INx/INx to Qx/Qx @1 GHz @ 50 MHz SELn to Qx	100	175 5	250 10	ps ns
t <sub>PD Tempco</sub>	Differential Propagation Delay Temperature Coeffic	ient		100		∆fs/°C
tskew	Output – Output skew (within device) (Note 13) Device – Device skew (t <sub>pdmax</sub> – t <sub>pdmin</sub> )			0 30	15 100	ps
t <sub>DC</sub>	Output Clock Duty Cycle (Reference Duty Cycle = 50%) f <sub>in</sub> = 1 GHz		45	50	55	%
$\Phi_{N}$	Phase Noise, f <sub>in</sub> = 1 GHz	10 kHz 100 kHz 1 MHz 10 MHz 20 MHz		-134 -136 -149 -150 -150		dBc
t <sub>∫ΦN</sub>	Integrated Phase Jitter (Figure 1) fin = 1GHz, 12 kHz	Hz - 20 MHz Offset (RMS)		35		fs
t <sub>JITTER</sub>	Random Clock Jitter, RJ(RMS), (Note 14) Deterministic Jitter, DJ (Note 15)			0.2	0.8 10	ps
	Crosstalk Induced Jitter (Adjacent Channel) (Note	16)			0.7	psRMS
V <sub>INPP</sub>	Input Voltage Swing (Differential Configuration) (No	te 17)	100		1200	mV
t <sub>r,</sub> , t <sub>f</sub>	Output Rise/Fall Times @ 1 GHz; (20% - 80%), Qx	κ, <mark>Qx</mark>	25	50	75	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 11. Measured using a  $V_{INPPmin}$  source, 50% duty cycle clock source. All output loading with external 50  $\Omega$  to  $V_{CC}$  2 V. Input edge rates 40 ps (20% 80%).
- 12. Output voltage swing is a single-ended measurement operating in differential mode.
- 13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the cross-point of the outputs.
- 14. Additive RMS jitter with 50% duty cycle clock signal.
- 15. Additive Peak-to-Peak data dependent jitter with input NRZ data at PRBS23.
- 16. Crosstalk is measured at the output while applying two similar clock frequencies that are asynchronous with respect to each other at the inputs.
- 17. Input voltage swing is a single-ended measurement operating in differential mode.

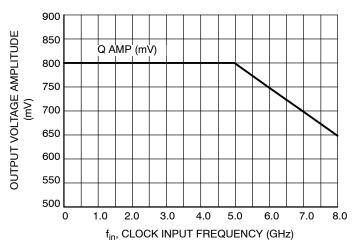


Figure 3. Clock Output Voltage Amplitude (V<sub>OUTPP</sub>) vs. Input Frequency (f<sub>in</sub>) at Ambient Temperature (Typical)

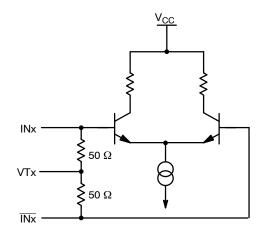


Figure 4. Input Structure

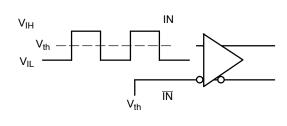


Figure 5. Differential Input Driven Single-Ended

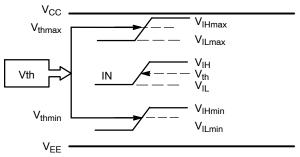


Figure 6. V<sub>th</sub> Diagram

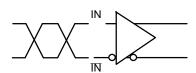


Figure 7. Differential Inputs Driven Differentially

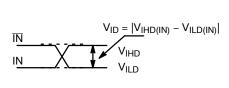


Figure 8. Differential Inputs Driven Differentially

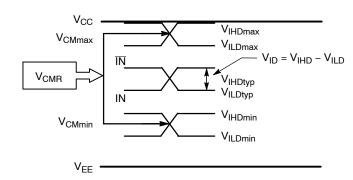


Figure 9. VCMR Diagram

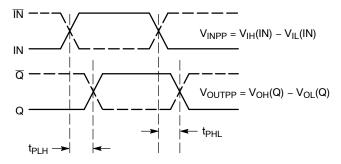


Figure 10. AC Reference Measurement

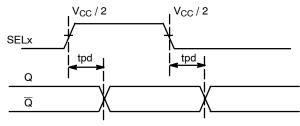


Figure 11. SELx to Qx Timing Diagram

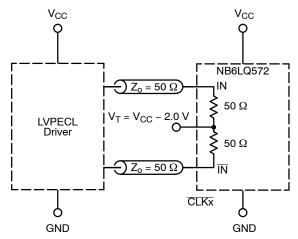


Figure 12. LVPECL Interface

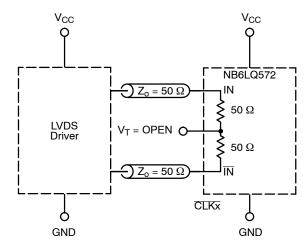


Figure 13. LVDS Interface

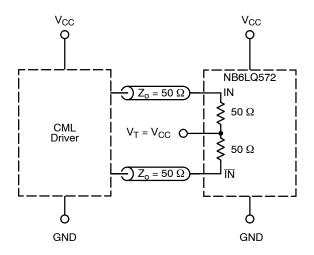


Figure 14. Standard 50  $\Omega$  Load CML Interface

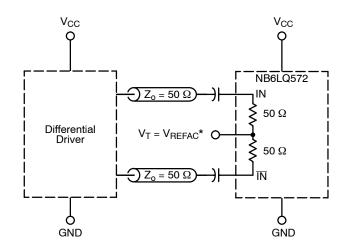


Figure 15. Capacitor–Coupled Differential Interface (V<sub>T</sub> Connected to External V<sub>REFAC</sub>)

\*V\_REFAC bypassed to ground with a 0.01  $\mu\text{F}$  capacitor.

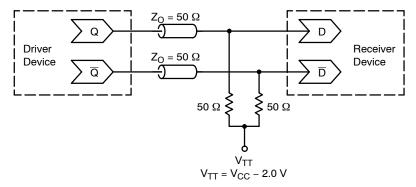


Figure 16. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices)

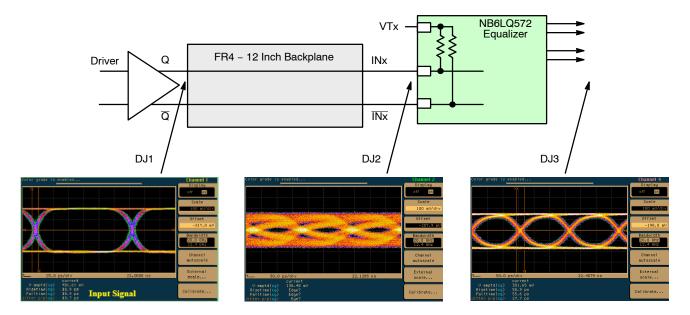


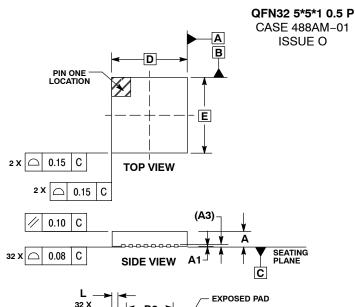
Figure 17. Typical NB6LQ572 Equalizer Application and Interconnect with PRBS23 Pattern at 6.5 Gbps

# **DEVICE ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NB6LQ572MNG	QFN-32 (Pb-Free)	74 Units / Rail
NB6LQ572MNR4G	QFN-32 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



**BOTTOM VIEW** 

В

0.10 С Α

0.05 С

Ф

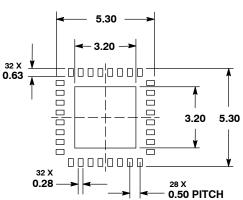
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#### NOTES:

- 1. DIMENSIONS AND TOLERANCING PER
- DIMENSION 5 AND TOLERANGING FEA ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.800	0.900	1.000		
A1	0.000	0.025	0.050		
А3	0.200 REF				
b	0.180	0.250	0.300		
D	5	.00 BSC	;		
D2	2.950	3.100	3.250		
Е	5.00 BSC				
E2	2.950	3.100	3.250		
е	0.500 BSC				
K	0.200				
L	0.300	0.400	0.500		

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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